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Customer No.: 31561
Application No.: 10/709,179
Docket No.: 10544-US-PA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: Ha, Nathan W.

Group Art Unit: 2814

In re PATENT APPLICATION of

Applicants : Chang et al.

Serial No. : 10/709,179

Filed : April 19, 2004

For : Stack-Type Multi-Chip Package
and Method of Fabricating Bumps
on the Backside of a Chip

AMENDMENT

) Attorney Docket: 10544-US-PA

)

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Dear Sir:

The Office Action dated October 13, 2005, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.